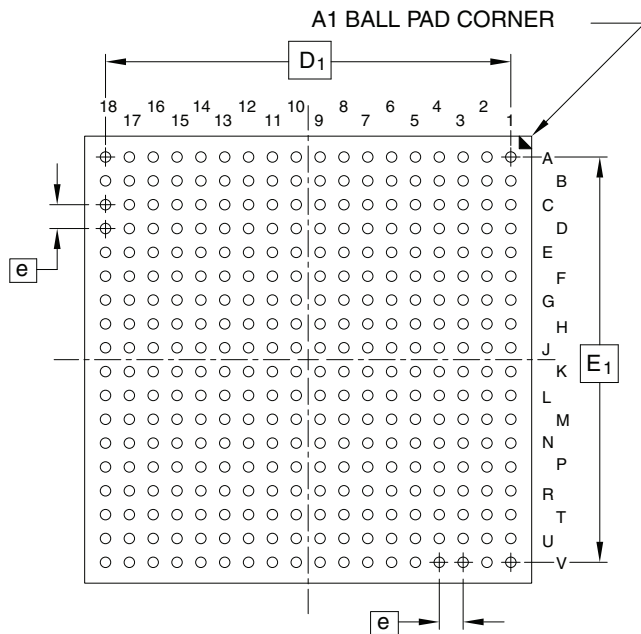
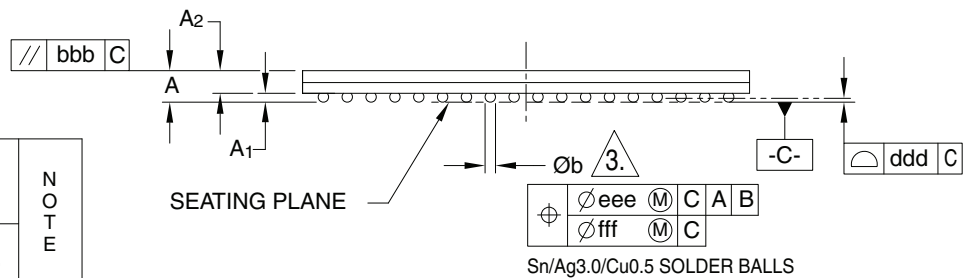
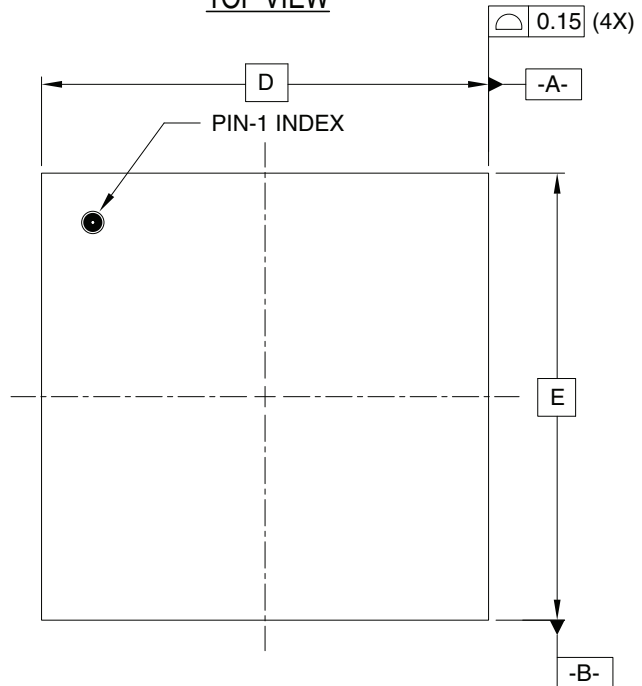


BOTTOM VIEW



TOP VIEW



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	1.00	<i>h</i>	1.50	3
A ₁	0.25	0.30	0.40	
A ₂	0.75	0.90	1.10	
D/E	15.00 BSC			
D ₁ /E ₁	13.60 BSC			
e	0.80 BSC			
Øb	0.35	0.40	0.45	
bbb	<i>h</i>	<i>h</i>	0.20	
ddd	<i>h</i>	<i>h</i>	0.10	
eee	<i>h</i>	<i>h</i>	0.15	
fff	<i>h</i>	<i>h</i>	0.08	
M	18			2

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- SYMBOL "M" IS THE PIN MATRIX SIZE
- 3.** DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
- THERE SHALL BE A MINIMUM CLEARANCE OF 0.25mm BETWEEN THE EDGE OF THE SOLDER BALL AND THE BODY EDGE
- CONFORMS TO JEDEC MO-275-KKAC-1

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.

Notice of Disclaimer

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